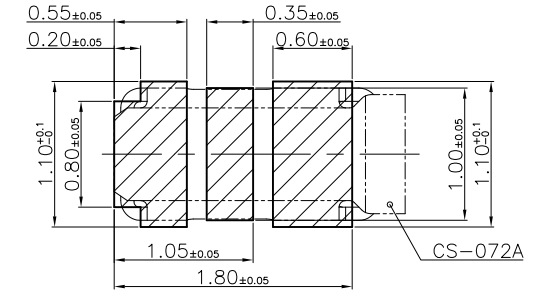
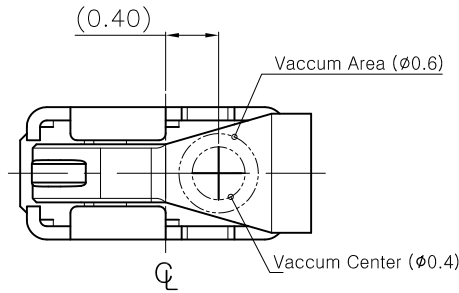
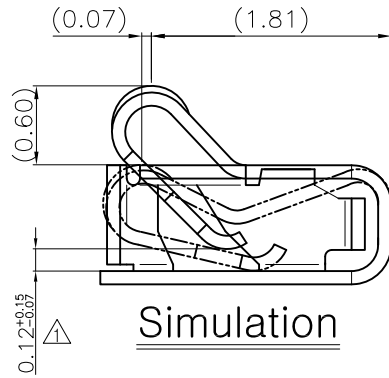
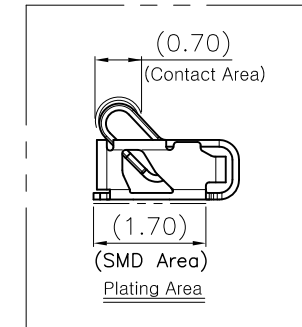


Rev No.	Description	Date	Name	Reviewed	Approved	Remark
△ X 3	고객사 요청으로 인한 Spec' 추가	2015.05.07	M.G.Son	Y.J.Park	S.K.Hong	-
△ X 1	고객사 요청으로 인한 Wall 무너짐 개선	2015.06.01	M.G.Son	Y.J.Park	S.K.Hong	-



RECOMMENDED PCB LAYOUT(Top View)
(Metal Mask Thick:0.1)



*NOTE

- PLATING
 - Contact Area : Au 0.05 μ m Min over Pd-Ni 0.2 μ m Min. over Ni 1.5~4.0 μ m.
 - SMD Area : Au 0.05 μ m Min over Ni 1.5~4.0 μ m.
 - Other Area : Ni 1.5~3.5 μ m.
- ☆: C.T.Q
- ☆: 평탄도 0.05 Max.
- Contact 가동거리 : 0.6mm
권장 Contact 높이 : 가동거리의 60~90% 범위 내
(0.36~0.54mm) => (0.96~1.14mm)
* CONTACT 가동거리(Max)는 0.6mm 이상으로 한다.
- 제품의 안정적 Contact을 위하여 Bending部 "B" 주위에 기구적인 간섭이 없을 것.

1	Contact	Ti-Cu		Note.1		t0.1		
No	Part name	Material		Finish		Remarks		
General Tolerance		Scale	N/S	Units	mm	Sheet	CS-072A ANTENNA CONTACT Customer Drawing	
Dimension	mm (°)	Date		2015.02.12		TITLE		
X	± 0.2	Y.J. Park 2015/02/12	-	-	S.K. Hong 2015/02/12			
X.X	± 0.15							
X.XX	± 0.1							
X.XXX	± 0.05							
ANGLE	± 2°	 협진커넥터(주) HYUPJIN CONNECTOR, Co., Ltd. 1 of 1				SW No.	RI-CS-072A-A1.DWG	Rev. 2
						DWG No.	CS-072A-A1	

